

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Original) A composite material comprising a porous semiconductor impregnated with at least one beneficial organic substance to a pore depth from the surface of the semiconductor of at least 5 microns, wherein the beneficial organic substance is present in an amount of at least 15 % by weight, based on the weight of the material.
2. (Original) A material according to claim 2 wherein the porous semiconductor is impregnated with at least one beneficial organic substance to a pore depth from the surface of at least 50 microns.
3. (Previously Presented) A material according to claim 1 wherein the porous semiconductor is doped or undoped silicon, germanium, silicon carbide or silicon nitride.
4. (Original) A material according to claim 3 wherein the porous semiconductor is silicon.
5. (Original) A material according to claim 4 wherein the silicon is resorbable.
6. (Original) A material according to claim 5 where the silicon is mesoporous.
7. (Previously Presented) A material according to claim 4 wherein the porous silicon has a porosity of from 40% to 90%.
8. (Previously Presented) A material according to claim 1 wherein the beneficial organic substance has a solubility in aqueous media of no more than 10mg/mL at a pH range 1-7.
9. (Previously Presented) A material according to claim 1 wherein the beneficial organic substance has a melting point of below 300⁰C.
10. (Original) A material according to claim 9 wherein the beneficial organic substance

has a melting point of below 100°C.

11. (Previously Presented) A material according to claim 1 wherein the beneficial organic substance is selected from chlorambucil, amitriptyline, ibuprofen, procaine, levamisole, plumbagin, cyclophosphamide, busulfan, dexamethasone, lauric acid, medroxy progesterone acetate, vitamin K, vitamin E, paclitaxel and rifampicin or a mixture thereof.

12. (Previously Presented) A material according to claim 1 wherein the beneficial organic substance is present in an amount of from 15% to 85% by weight, based on the weight of the material.

13. (Previously Presented) A material according to claim 1 wherein the beneficial organic substance is distributed substantially uniformly through the pores of the semiconductor.

14.-41. (Canceled).

42. (New) A composite material comprising a porous semiconductor impregnated with at least one beneficial organic substance with greater than 5 carbon atoms to a pore depth from the surface of the semiconductor of at least 5 microns, wherein the beneficial organic substance is present in an amount of at least 15 % by weight, based on the weight of the material.

43. (New) A material according to claim 42 wherein the organic material is selected from antibodies, peptides and genetic constructs.

44. (New) A material according to claim 43 wherein the porous semiconductor is impregnated with at least one beneficial organic substance to a pore depth from the surface of at least 50 microns.

45. (New) A material according to claim 42 wherein the porous semiconductor is doped or undoped silicon, germanium, silicon carbide or silicon nitride.

46. (New) A material according to claim 42 wherein the porous semiconductor is

silicon.

47. (New) A material according to claim 46 wherein the silicon is resorbable.
48. (New) A material according to claim 47 where the silicon is mesoporous.
49. (New) A material according to claim 46 wherein the porous silicon has a porosity of from 40% to 90%.
50. (New) A material according to claim 42 wherein the beneficial organic substance has a solubility in aqueous media of no more than 10mg/mL at a pH range 1-7.
51. (New) A material according to claim 42 wherein the beneficial organic substance has a melting point of below 300⁰C.
52. (New) A material according to claim 51 wherein the beneficial organic substance has a melting point of below 100⁰C.
53. (New) A material according to claim 42 wherein the beneficial organic substance is selected from chlorambucil, amitriptyline, ibuprofen, procaine, levamisole, plumbagin, cyclophosphamide, busulfan, dexamethasone, lauric acid, medroxy progesterone acetate, vitamin K, vitamin E, paclitaxel and rifampicin or a mixture thereof.
54. (New) A material according to claim 42 wherein the beneficial organic substance is present in an amount of from 15% to 85% by weight, based on the weight of the material.
55. (New) A material according to claim 42 wherein the beneficial organic substance is distributed substantially uniformly through the pores of the semiconductor.